

APT2012PD1C

2.0 x 1.25 mm Photodiode

DESCRIPTION

· Made with NPN silicon photodiode chips

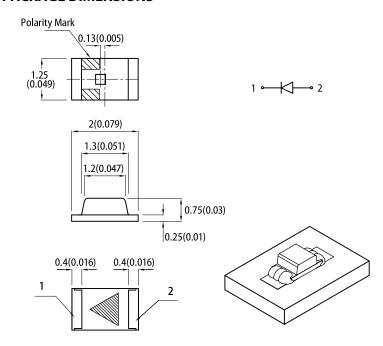
FEATURES

- 2.0 mm x 1.25 mm SMD LED, 0.75 mm thickness
- · Mechanically and spectrally matched to infrared emitting LED lamp
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- RoHS compliant

APPLICATIONS

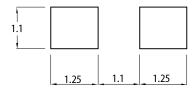
- Infrared applied systems
- · Optoelectronic switches
- · Photodetector control circuits
- · Sensor technology

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: ± 0.1)



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
 3. The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Maximum Ratings	Units
Power Dissipation	150	mW
Operating Temperature	-40 to +85	°C
Storage Temperature	-40 to +85	°C

Note:
1. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

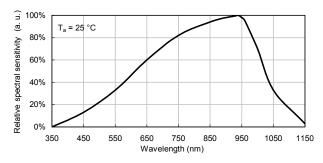


ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

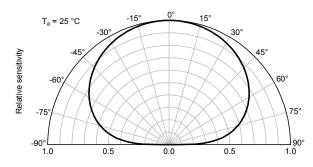
Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Reverse Break down Voltage	V _{(BR)R}	33	170	-	V	I _R = 100uA H = 0mW/cm ²
Reverse Dark Current	ID _(R)	-	-	10	nA	$V_R = 10V$ H = 0mW/cm ²
Open Circuit Voltage	V _{oc}	1	390	-	mV	λ = 940nm H = 5mW/cm²
Rise Time	T _R	-	6	-	nS	$V_R = 10V$ $\lambda = 940$ nm $R_L = 1000\Omega$
Fall Time	T _F	-	6	-	nS	
Light current	I _S	4	8	-	uA	$V_R = 5V$ $Ee = 0.08 mW/cm^2$ $\lambda = 940 nm$
Total Capacitance	Ст	-	5	-	pF	$V_R = 10V$ $F = 1MHZ$ $H = 0mW/cm^2$
Range of spectral bandwidth	λ _{0.1}	420	-	1120	nm	-
Wavelength of peak sensitivity	λ_p	-	940	-	nm	-
Angle of half sensitivity	201/2	-	160	-	deg	-

TECHNICAL DATA

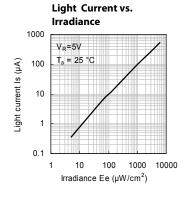
RELATIVE SPECTRAL SENSITIVITY vs. WAVELENGTH

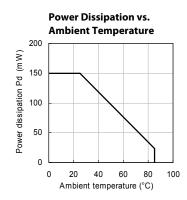


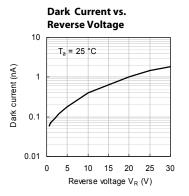
RELATIVE RADIANT SENSITIVITY vs. ANGULAR DISPLACEMENT

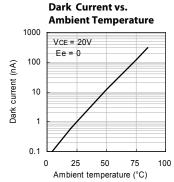


PHOTODIODE











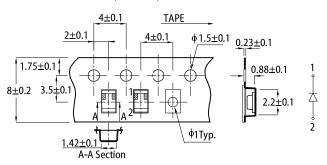
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max 6°C/s max. 200 150 Temperature pre-heating 100 above 217°C 60~150s 150~200°C 60~120s 50 50 100 150 200 250 Time

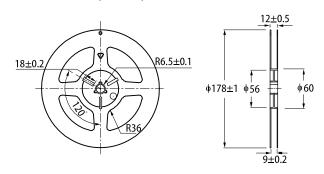
- Don't cause stress to the LEDs while it is exposed to high temperature.
- 2. The maximum number of reflow soldering passes is 2 times.

 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

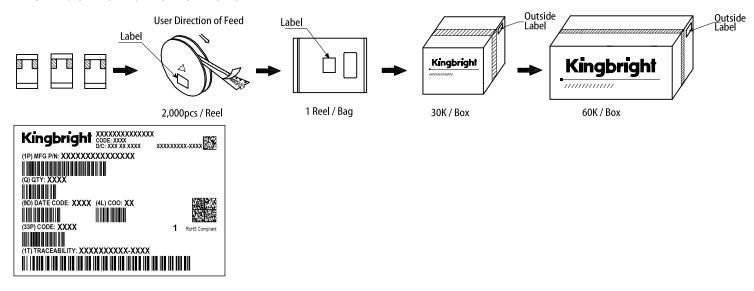
TAPE SPECIFICATIONS (units:mm)



REEL DIMENSION (units:mm)



PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

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